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(71) Applicant *(for all designated States except US)*: **HANMI SEMICONDUCTOR CO., LTD.** [KR/KR]; 532-2, Gajwa-dong, Seo-ku, Incheon 404-250 (KR).

(72) Inventor; and

(75) Inventor/Applicant *(for US only)*: **KWAK, Nho-Kwon** [KR/KR]; 805-1002, Poonglim Apt., 2787-2, Unseo-dong, Jung-ku, Incheon 400-833 (KR).

(74) Agent: **OH, Wi-Hwan**; 5th Fl, Eunseong Bldg., 601-18, Yeoksam-dong, Kangnam-gu, Seoul 135-080 (KR).

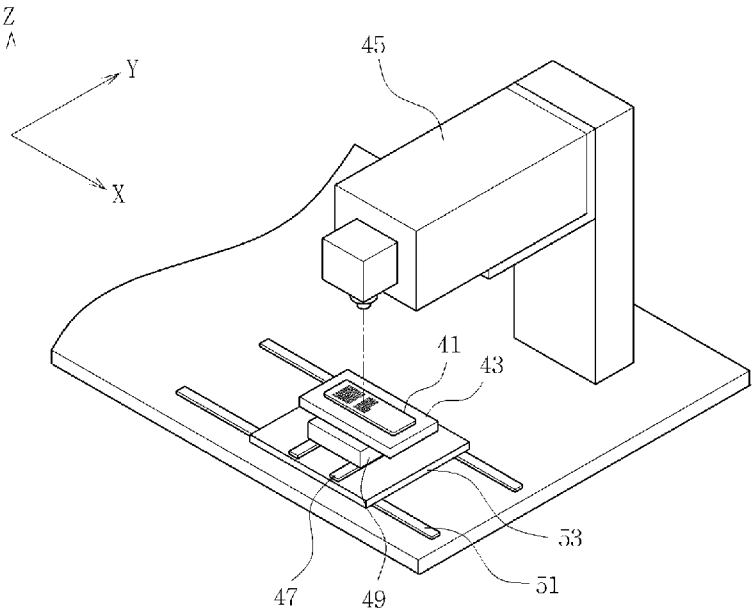
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(54) Title: APPARATUS AND METHOD FOR MANUFACTURING ABSORPTION PAD



(57) Abstract: Disclosed are an apparatus and a method for manufacturing an absorption pad used for picking up a package or a strip during a semiconductor manufacturing process. The apparatus includes a workpiece transfer device on which a workpiece is mounted, a laser generator installed above the workpiece transfer device while being spaced apart from the workpiece transfer device by a predetermined distance, a driving unit for moving the workpiece transfer device and the laser generator relative to each other, and a controller for controlling the laser generator. It is possible to precisely form patterns having various sizes and shapes according to use of the absorption pad and the size of the package. Processing conditions for the workpiece are standardized, so that the processing time and manufacturing cost for the absorption pad are minimized.

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